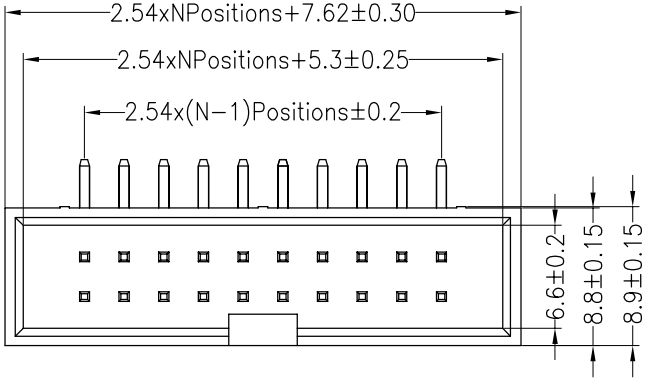
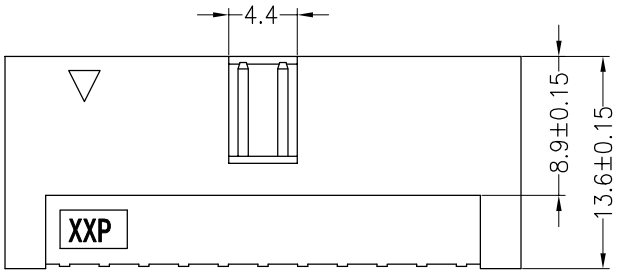
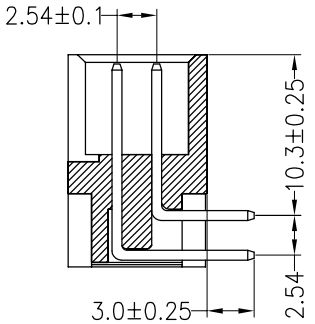
HSF RoHS

SPECIFICATIONS
Rated Current:3.0AMP
Contact Resistance:20mΩ Max
Withstand Voltage:1000V AC/DC
Insulation Resistance:1000MΩ Min
Operation Temperature:−40°c to +105°c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V−0)
Standard: PA6T
Max.Processing Temp: 230°C for 30−60 seconds
(260°C for 10 seconds)



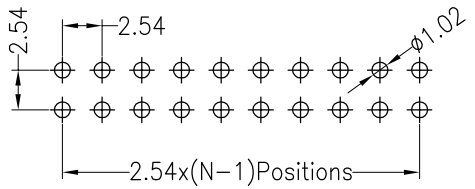




Ordering Information

3217 XX R XX X B K00 X 0X

No.of Pins	Contact Plating		Insulator Material		Packing
6−−64	G0:Gold Flash		Option		T=Tube
	G1:1U" Gold		A=BK−PBT		A=Tray
	G2:1.5U" Gold		B=BK−PA66		
	G3:2U" Gold		C=BK−PA6T		
	G4:3U" Gold		D=BK−PA46		
	G5:5U" Gold		E=BK−PA9T		
	S0:Gold Flash/Tin		F=BK−LCP		
	SN:Tin				



Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A0	2015.01.28	NEW DRAWING	

OPERATION		DRAW	Liu Miao	15.01.28	SCALE	FIT
X.X	±0.30				UNIT	mm
X.XX	±0.20	CHECK			SIZE	A4
X.XXX	±0.10				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	
DIM	TOL					

WFD CONN 深圳市旺富达电子有限公司
SHEN ZHEN WFD ELECTRONICS CO., LTD

PART NO.	3217XXRXXXBK00X0X
TITLE:	2.54mm Box Header H13.6mm 90°